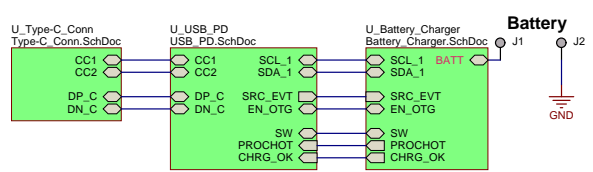
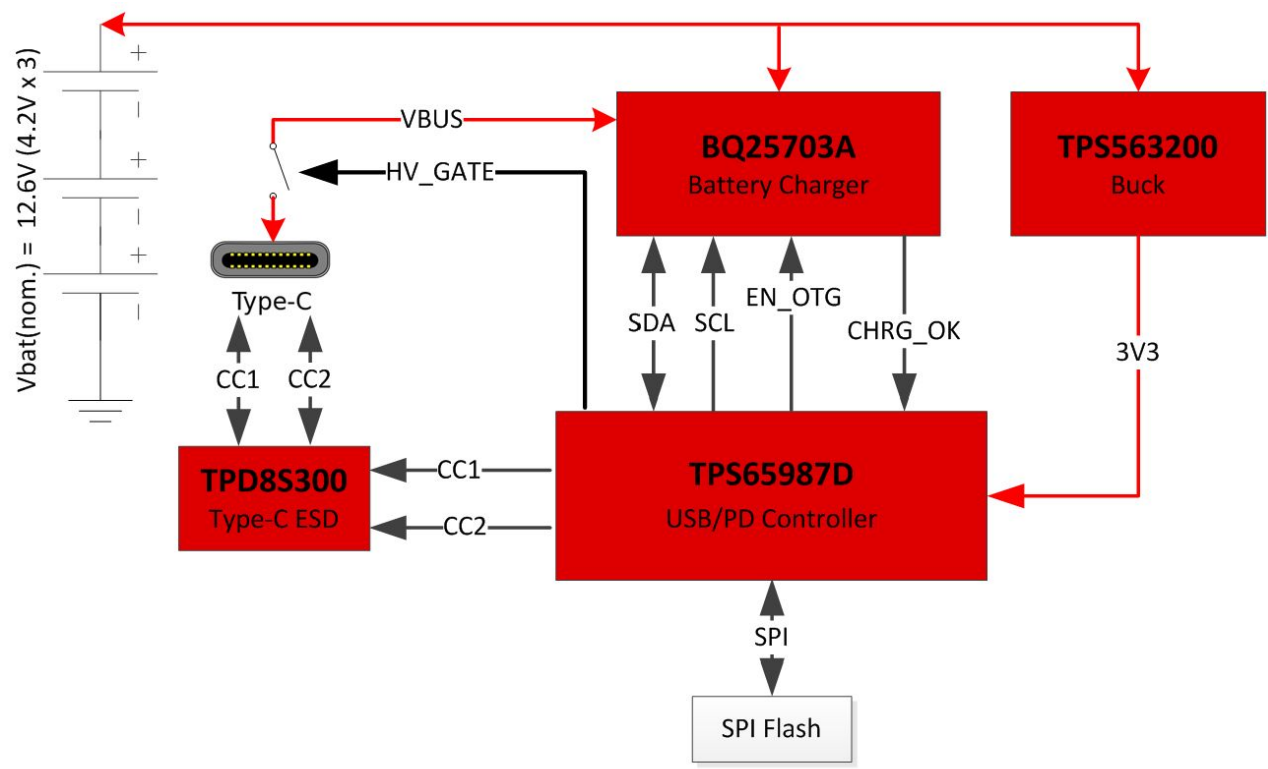
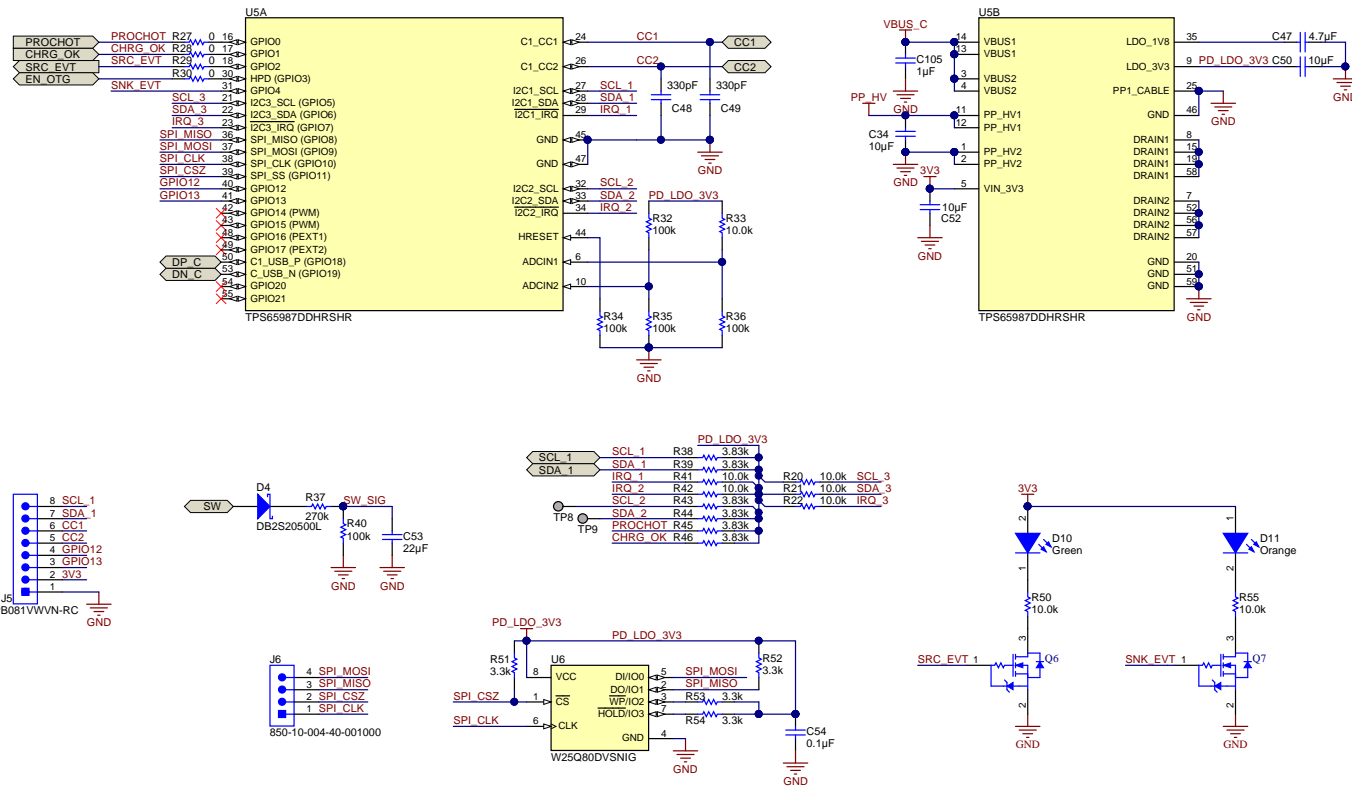


Revision History				
Rev	ECN #	Date of Change	Changed By	Notes
1.0	N/A	08/14/2018	Rahul Sharma	




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Orderable: EVM_orderable	Designed for: Internal Release	Mod. Date: 14-Aug-18	 http://www.ti.com
TID #: TIDA-01627	Project Title: Power Bank		
Number: N/A	Rev: E1	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: Base	Sheet: 1 of 4	
Drawn By: Rahul Sharma	File: Power Bank_CoverSheet.SchDoc	Size: B	
Engineer: Rahul Sharma	Contact: http://www.ti.com/support		



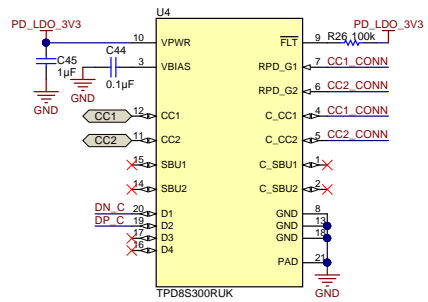
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Orderable: EVM_orderable	Designed for: Internal Release	Mod. Date: 14-Aug-18
TID #: TIDA-01627	Project Title: Power Bank	
Number: N/A	Rev: E1	Sheet Title:
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Drawn By:	File: USB_PD_SchDoc	Size: B
Engineer: Rahul Sharma	Contact: http://www.ti.com/support	

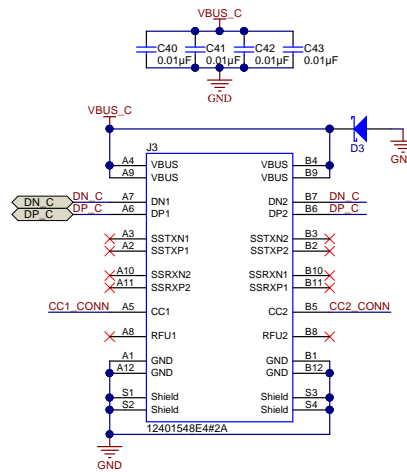


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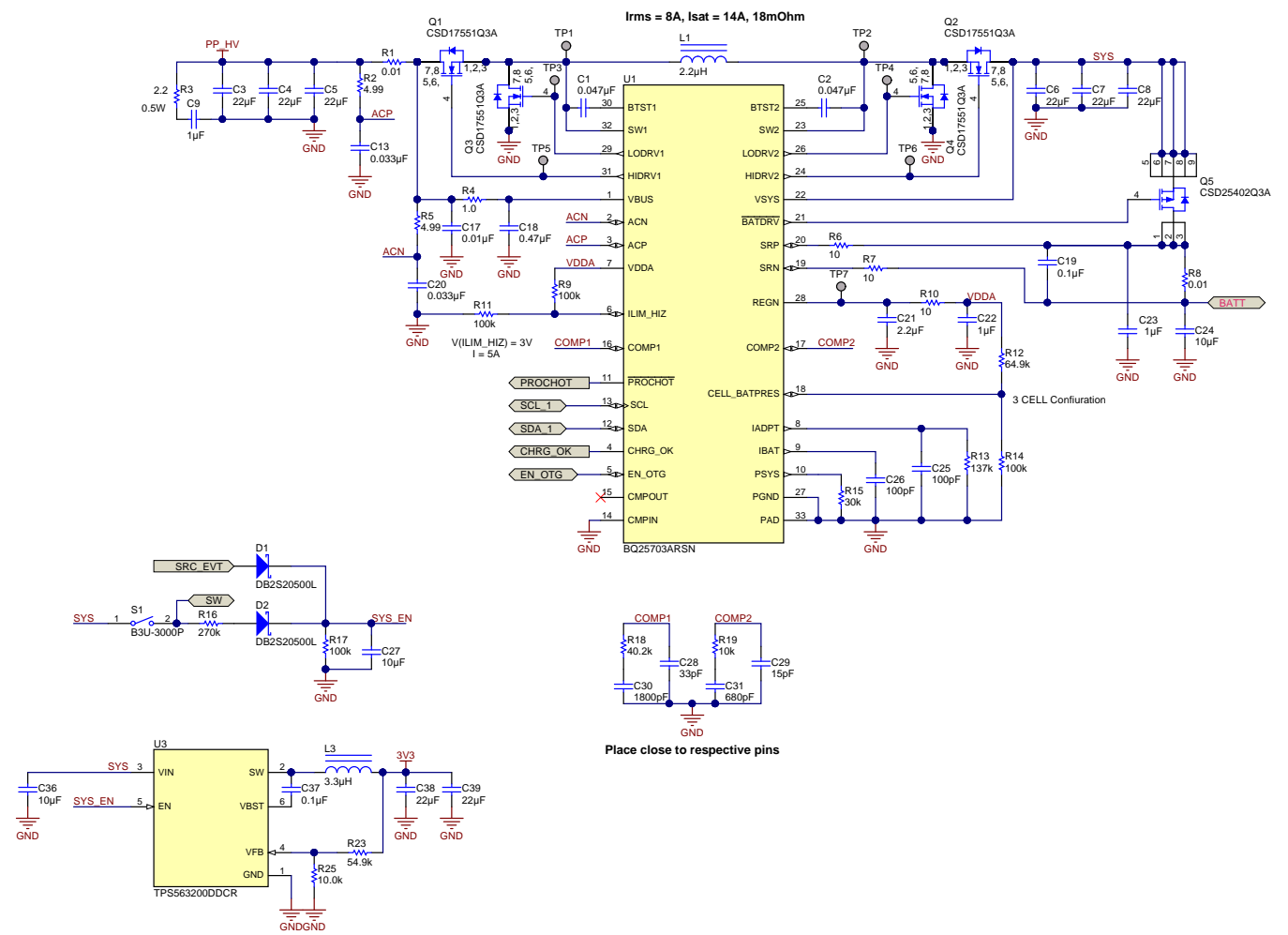


Place close to Type-C receptacle



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TID #: TIDA-01627	Project Title: Power Bank	
Number: N/A	Rev: E1	Sheet Title:
SVN Rev. Version control disabled	Assembly Variant: Base	Sheet: 2 of 4
Drawn By:	File: Type-C_Conn.SchDoc	Size: B
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Orderable: EVM_orderable	Designed for: Internal Release	Mod. Date: 14-Aug-18
TID #: TIDA-01627	Project Title: Power Bank	
Number: N/A	Rev: E1	Sheet Title:
SVN Rev. Version control disabled	Assembly Variant: Base	Sheet: 2 of 4
Drawn By:	File: Battery_Charger_SchDoc	Size: B
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